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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	41984000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxmb5r3f40c2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCD_FPLL</sub>	PLL digital power supply	-0.5	1.8	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	-0.5	3.4	V
V <sub>I</sub>	DC input voltage	-0.5	3.8	V
T <sub>J</sub>	Operating junction temperature	-55	125	°C
T <sub>STG</sub>	Storage temperature (No bias)	-65	150	°C
I <sub>OUT</sub>	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHIP_R</sub>	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

# **Maximum Allowed Overshoot and Undershoot Voltage**

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

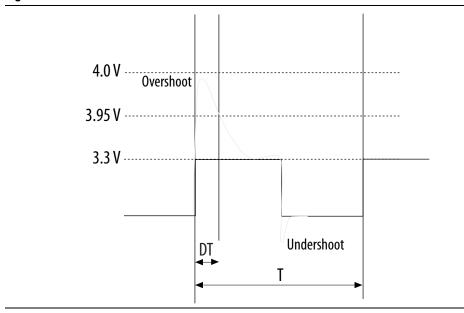
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Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

**Table 5. Maximum Allowed Overshoot During Transitions** 

Symbol	Description	Condition (V)	Overshoot Duration as % @ T <sub>J</sub> = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Figure 1. Stratix V Device Overshoot Duration



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Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
			0.82	0.85	0.88	
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V <sub>CCT_GXBL</sub>	Transmitter analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
	Transmitter analog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
		GX, GS, GT	0.82	0.85	0.88	V
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)		0.87	0.90	0.93	
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

### Notes to Table 7:

<sup>(1)</sup> This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

<sup>(2)</sup> Refer to Table 8 to select the correct power supply level for your design.

<sup>(3)</sup> When using ATX PLLs, the supply must be 3.0 V.

<sup>(4)</sup> This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
		1.5	0.273	
		1.2	0.317	

### Note to Table 13:

(1) Valid for a  $V_{\text{CCIO}}$  range of  $\pm 5\%$  and a temperature range of  $0^\circ$  to  $85^\circ\text{C}.$ 

## **Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices** 

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

### **Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I <sub>IOPIN (DC)</sub>	DC current per I/O pin	300 μΑ
I <sub>IOPIN (AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX (DC)</sub>	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX (DC)</sub>	DC current per transceiver receiver pin	50 mA

### Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)			V <sub>REF</sub> (V)		V <sub>TT</sub> (V)			
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах	
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	V <sub>REF</sub> – 0.04	$V_{REF}$	V <sub>REF</sub> + 0.04	
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04	
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>	
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>	
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	0.49 * V <sub>CCIO</sub>	0.5 * VCCIO	0.51 * V <sub>CCIO</sub>	
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V <sub>CCIO</sub> /2	_	
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V <sub>CCIO</sub> /2	_	
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.53 * V <sub>CCIO</sub>	_	V <sub>CCIO</sub> /2	_	
HSUL-12	1.14	1.2	1.3	0.49 * V <sub>CCIO</sub>	0.5 * V <sub>CCIO</sub>	0.51 * V <sub>CCIO</sub>	_	_	_	

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V <sub>IL(D(</sub>	<sub>c)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I (mA)	l <sub>oh</sub>	
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>ol</sub> (mA)	(mA)	
SSTL-2 Class I	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.608	V <sub>TT</sub> + 0.608	8.1	-8.1	
SSTL-2 Class II	-0.3	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.31	V <sub>REF</sub> + 0.31	V <sub>TT</sub> – 0.81	V <sub>TT</sub> + 0.81	16.2	-16.2	
SSTL-18 Class I	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	V <sub>TT</sub> – 0.603	V <sub>TT</sub> + 0.603	6.7	-6.7	
SSTL-18 Class II	-0.3	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	V <sub>CCIO</sub> + 0.3	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	0.28	V <sub>CCIO</sub> - 0.28	13.4	-13.4	
SSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	8	-8	
SSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.175	V <sub>REF</sub> + 0.175	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	16	-16	
SSTL-135 Class I, II	_	V <sub>REF</sub> – 0.09	V <sub>REF</sub> + 0.09	_	V <sub>REF</sub> – 0.16	V <sub>REF</sub> + 0.16	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_	
SSTL-125 Class I, II	_	V <sub>REF</sub> – 0.85	V <sub>REF</sub> + 0.85	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_	
SSTL-12 Class I, II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.2 * V <sub>CCIO</sub>	0.8 * V <sub>CCIO</sub>	_	_	

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

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# **Switching Characteristics**

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

# **Transceiver Performance Specifications**

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V	PCML,	, 2.5-V PCN HCSL	1L, Diffe	rential	LVPECL, L\	/DS, and
Statiuatus	RX reference clock pin			1.4-V PCMI	_, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Input Reference Clock Frequency (CMU PLL) (8)	_	40	_	710	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (8)	_	100	_	710	100	_	710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_	_	400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_	_	400	_	_	400	ps
Duty cycle	_	45		55	45	_	55	45		55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30	_	33	30	_	33	kHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on- chip termination resistors <sup>(21)</sup>	100–Ω setting	_	100 ± 30%		_	100 ± 30%	_	_	100 ± 30%	_	Ω
	120–Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V <sub>ICM</sub> (AC and DC	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupled)	$V_{CCR\_GXB} = \\ 1.0 \text{ V/1.05 V} \\ \text{full} \\ \text{bandwidth}$	_	700	_	_	700	_	_	700	_	mV
	V <sub>CCR_GXB</sub> = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t <sub>LTR</sub> (11)	_	_	_	10	_	_	10	_	_	10	μs
t <sub>LTD</sub> (12)	_	4	_		4			4			μs
t <sub>LTD_manual</sub> (13)	_	4	_		4			4			μs
t <sub>LTR_LTD_manual</sub> (14)		15			15		_	15	_		μs
Run Length		_	_	200	_		200	_	-	200	UI
Programmable equalization (AC Gain) (10)	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Trar	sceive Grade	r Speed 2	Tran	Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t <sub>pll_lock</sub> (16)	_	_	_	10	_	_	10	_	_	10	μs

#### Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the  $V_{CCR\_GXB}$  power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR\_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t<sub>LTR</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t<sub>I TD</sub> is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t<sub>LTR\_LTD\_manual</sub> is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll\ powerdown}$  is the PLL powerdown minimum pulse width.
- (16) t<sub>nll lock</sub> is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V<sub>ID</sub> after device configuration is equal to 4 × (absolute V<sub>MAX</sub> for receiver pin V<sub>ICM</sub>).
- (19) For ES devices,  $R_{REF}$  is 2000  $\Omega$  ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Mada (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode <sup>(2)</sup>	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

### Notes to Table 25:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

<sup>(3)</sup> The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5)  $^{(1)}$ 

Symbol/	Conditions	5	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Reference Clock	•	•	•	•	•	•	•	
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	/IL, 1.4-V PC	ML, 1.5-V P	CML, 2.5-V and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS,
Standards	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	<b>;</b>
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz
Rise time	20% to 80%	_	_	400	_	_	400	
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps
Duty cycle	_	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4	_	_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin		1050/1000	2)		1050/1000	2)	mV
	RX reference clock pin	1	.0/0.9/0.85	(22)	1	.0/0.9/0.85	(22)	V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/	Symbol/ Description Conditions		Transceivei peed Grade		T Sp	Unit		
Description		Min	Тур	Max	Min	Тур	Max	
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs

#### Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR\_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t<sub>LTB</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) tLTD is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t<sub>LTR\_LTD\_manual</sub> is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V<sub>ID</sub> after device configuration is equal to 4 × (absolute V<sub>MAX</sub> for receiver pin V<sub>ICM</sub>).
- (17) For ES devices, RREF is 2000  $\Omega$  ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR\_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

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Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance									
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit			
		Modes us	ing Three	DSPs	•						
One complex 18 x 25	425	425	415	340	340	275	265	MHz			
Modes using Four DSPs											
One complex 27 x 27	465	465	465	380	380	300	290	MHz			

# **Memory Block Specifications**

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resour	Resources Used		Performance								
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit		
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz		
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz		
IVILAD	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz		
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz		

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# **Periphery Performance**

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

# **High-Speed I/O Specification**

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

_														
Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
f <sub>HSCLK_in</sub> (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f <sub>HSCLK_in</sub> (input clock frequency) Single Ended I/O Standards <sup>(3)</sup>	Clock boost factor W = 1 to 40 (4)	5		800	5	_	800	5		625	5		525	MHz
f <sub>HSCLK_in</sub> (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (4)	5		520	5	_	520	5		420	5		420	MHz
f <sub>HSCLK_OUT</sub> (output clock frequency)	_	5		800	5	_	800	5		625 (5)	5		525 (5)	MHz

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Combal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I4	4	II.a.i.k
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f <sub>HSDR</sub> (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t <sub>x Jitter</sub> - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t <sub>x Jitter</sub> - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I4	4	
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t <sub>DUTY</sub>	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t <sub>RISE</sub> & t <sub>FALL</sub>	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150		_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_		300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f <sub>HSDRDPA</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
1FF ×32	Enabled	Disabled	8
	Enabled	Enabled	8

#### Note to Table 49:

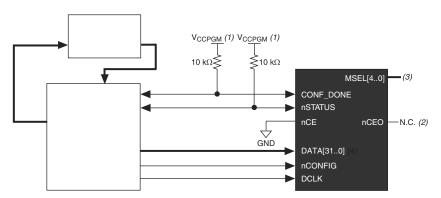
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



### Notes to Figure 11:

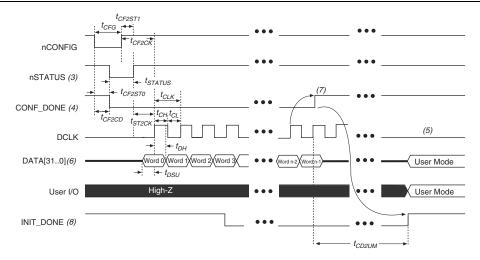
- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V<sub>CCPGM</sub> must be high enough to meet the V<sub>IH</sub> specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V<sub>CCPGM</sub>.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP  $\times 8$ , use DATA [7..0]. If you use FPP  $\times 16$ , use DATA [15..0].

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# FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT\_DONE</code> pin is configured into the device, the <code>INIT\_DONE</code> goes low.

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Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}}$ + (8576 $\times$ CLKUSR period)	_	_

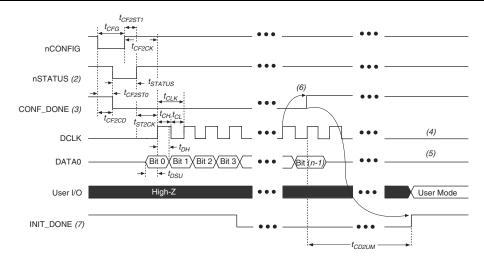
#### Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

# **Passive Serial Configuration Timing**

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



#### Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nCONFIG low to nSTATUS low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μ\$
t <sub>STATUS</sub>	nSTATUS low pulse width	268	1,506 <sup>(1)</sup>	μS
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(2)</sup>	μS
t <sub>CF2CK</sub> (5)	nCONFIG high to first rising edge on DCLK	1,506	<del></del>	μS
t <sub>ST2CK</sub> (5)	nSTATUS high to first rising edge of DCLK	2	_	μS
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	<del></del>	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	<del></del>	S
f <sub>MAX</sub>	DCLK frequency	_	125	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum  DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}}$ + (8576 × CLKUSR period) $^{(4)}$	_	_

### Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.
- (5) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

## Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles <sup>(1)</sup>
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP (2)	125 MHz	8576
DCLK	PS, FPP	125 MHz	

### Notes to Table 55:

- $(1) \quad \text{The minimum number of clock cycles required for device initialization}.$
- (2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.